

# CIPEL Distribution S.A.

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## Auxiliary products for the lamination of multilayer Printed Circuit Boards

### EDIRE

High temperature resistant **Release Film** particularly suitable for the manufacture of printed circuit boards Multilayers. It is designed for applications with temperatures up to 200 °C. The film is free of embedded foreign particles

**Available thicknesses : 25μ, 38μ et 50μ.**

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### EDIRE-STL

Release film (PTFE) is best suited for laminating-press cycles with very high temperature up to 260°C - 180min.

**Available thicknesses : 25μ, 38μ et 50μ.**

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### EPAPRESS

White press-pad made of purified cellulose and cotton. This press padding is excellent pressing tool of rigid multi-layers circuits. The press pads may be used more than once. For use up to approximately 195 ° C.

**Available thicknesses: 0.60, 0.90, 1,4mm**

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### EPAPRESS-3L 600

"paper-clad" both sides releasable, white colour. The "paper-clad" is made of rein selected Cellulose mixed with some Cotton, laminated with two Release Films 25μ thick. For Lamination press-cycle control up to 195°C

**Available thicknesses : 0.60, 0.90mm.**

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### CMY-190NS

Release-Conformal Film **CMY-190NS**, PBT/TPEE-Foil based **-190 μm thick**, is best suited for the pressure equalization by Lamination of Cover-Layers to Flexible Printed Circuit Boards. It reduces excessive "squeeze-out" and effectively drives adhesive or resin flow into designed areas.